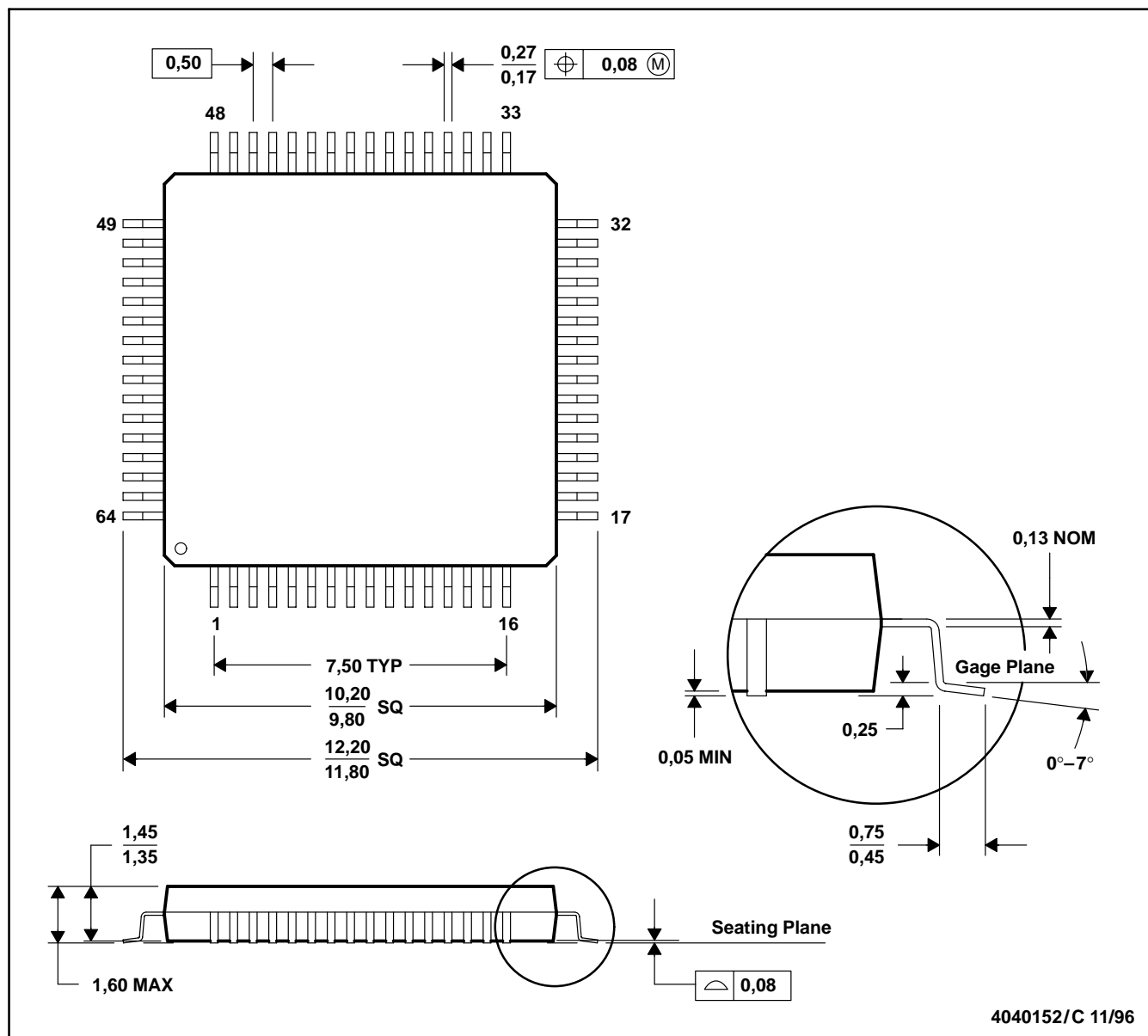


PM (S-PQFP-G64)

PLASTIC QUAD FLATPACK



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Falls within JEDEC MS-026
 - May also be thermally enhanced plastic with leads connected to the die pads.

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